| L Number | Hits    | Search Text   | DB        | Time stamp       |
|----------|---------|---|-----------|------------------|
| 1        | 1168    | ((438/690) or (438/750) or (438/734) or (438/737)).CCLS.  | USPAT;    | 2004/09/21 13:20 |
|          |         | , | US-PGPUB; |                  |
|          |         |   | EPO; JPO; |                  |
|          |         |   | DERWENT;  |                  |
|          |         |   | IBM TDB   |                  |
| -        | 16      | US-5164815-\$.DID. OR US-5313102-\$.DID. OR   | USPAT;    | 2004/09/18 19:20 |
|          |         | US-5476566-\$.DID. OR US-5583372-\$.DID. OR   | US-PGPUB; | 2004/00/10 10:20 |
|          |         | US-0618406-\$.DID. OR US-0624567-\$.DID. OR   | EPO; JPO; |                  |
|          |         | US-0625819-\$.DID. OR US-0627997-\$.DID. OR   | DERWENT;  |                  |
|          |         | US-6403449-\$.DID. OR US-0650668-\$.DID. OR   | IBM_TDB   |                  |
| ]        |         | US-0653441-\$.DID.  | IDM_IDB   |                  |
|          | 23      |   | USPAT:    | 2004/09/18 19:21 |
| -        | 23      | US-5476566-\$.DID. OR US-5583372-\$.DID. OR   | US-PGPUB: | 2004/09/10 19.21 |
|          |         | US-6184064-\$.DID. OR US-6245677-\$.DID. OR   | , , ,     |                  |
|          |         |   | EPO; JPO; |                  |
|          |         | US-6258198-\$.DID. OR US-6279976-\$.DID. OR   | DERWENT;  |                  |
|          |         | US-6403449-\$.DID. OR US-6506681-\$.DID. OR   | IBM_TDB   |                  |
|          | 00400   | US-6534419-\$.DID.  |           | 000440044040     |
| -        | 60162   | backside  | USPAT;    | 2004/09/18 19:40 |
|          |         |   | US-PGPUB; |                  |
|          |         |   | EPO; JPO; |                  |
|          |         |   | DERWENT;  |                  |
|          | 4000:   |   | IBM_TDB   |                  |
| -        | 1632127 | chip or die or dice or ic or integrated adj circuit   | USPAT;    | 2004/09/20 18:59 |
|          |         |   | US-PGPUB; |                  |
|          |         |   | EPO; JPO; |                  |
|          |         |   | DERWENT;  |                  |
|          |         |   | IBM_TDB   |                  |
| -        | 2185088 | polymer or epoxy or epoxies or silicone or urethane or siloxane or  | USPAT;    | 2004/09/20 14:46 |
|          |         | parylene  | US-PGPUB; |                  |
|          |         |   | EPO; JPO; |                  |
|          |         |   | DERWENT;  |                  |
|          |         |   | IBM_TDB   |                  |
| 1-       | 1929343 | coat\$4   | USPAT;    | 2004/09/18 19:44 |
|          |         |   | US-PGPUB; |                  |
|          |         |   | EPO; JPO; |                  |
| İ        |         |   | DERWENT;  |                  |
|          |         |   | IBM TDB   |                  |
| -        | 293421  | cmp or chemical adj mechanical or polish\$4 or planariz\$4 or   | USPAT;    | 2004/09/20 11:42 |
| 1        |         | planaris\$4   | US-PGPUB; |                  |
|          |         |   | EPO; JPO; |                  |
|          |         |   | DERWENT;  |                  |
|          |         |   | IBM TDB   |                  |
| -        | 0       | backside near4 (chip or die or dice or ic or integrated adj circuit)  | USPAT;    | 2004/09/18 19:46 |
|          | _       | near8 coat\$4 near4 (polymer or epoxy or epoxies or silicone or   | US-PGPUB; |                  |
|          |         | urethane or siloxane or parylene) near6 (cmp or chemical adj  | EPO; JPO; |                  |
|          |         | mechanical or polish\$4 or planariz\$4 or planaris\$4)  | DERWENT;  | •                |
|          |         | , , ,,,, -,   | IBM TDB   |                  |
| -        | 0       | backside near4 (chip or die or dice or ic or integrated adj circuit)  | USPAT;    | 2004/09/18 19:47 |
|          | J       | same coat\$4 same (polymer or epoxy or epoxies or silicone or   | US-PGPUB; | =30              |
|          |         | urethane or siloxane or parylene) same (cmp or chemical adj   | EPO; JPO; |                  |
| 1        |         | mechanical or polish\$4 or planariz\$4 or planaris\$4)  | DERWENT;  |                  |
|          |         |   | IBM TDB   |                  |
| -        | 13      | backside near4 (chip or die or dice or ic or integrated adj circuit)  | USPAT;    | 2004/09/20 13:24 |
|          | .0      | and backside same (polymer or epoxy or epoxies or silicone or   | US-PGPUB; |                  |
|          |         | urethane or siloxane or parylene) same (cmp or chemical adj   | EPO; JPO; |                  |
|          |         | mechanical or polish\$4 or planariz\$4 or planaris\$4)  | DERWENT;  | :                |
| ļ l      |         | moonamod of policity of plandil244 of plandil544)   | IBM TDB   |                  |
| 1_       | 8       | backside near4 (chip or die or dice or ic or integrated adj circuit)  | USPAT;    | 2004/09/18 20:20 |
|          | 0       | and backside near8 coat\$4 near8 ((cmp or chemical adj  |           | 2004/09/10 20:20 |
|          |         | mechanical or polish\$4 or planariz\$4 or planaris\$4) or   | US-PGPUB; |                  |
|          |         |   | EPO; JPO; |                  |
|          |         | backgrind\$)  | DERWENT;  |                  |
| L        |         |   | IBM_TDB   |                  |

|          |         |   |                        | _                |
|----------|---------|---|------------------------|------------------|
| -        | 8       | (backside near4 (chip or die or dice or ic or integrated adj circuit)   | USPAT;                 | 2004/09/18 20:17 |
|          |         | and backside near8 coat\$4 near8 ((cmp or chemical adj  | US-PGPUB;              |                  |
|          |         | mechanical or polish\$4 or planariz\$4 or planaris\$4) or   | EPO; JPO;              |                  |
| ·        | ł       | backgrind\$)) not (backside near4 (chip or die or dice or ic or   | DERWENT;               |                  |
|          |         | integrated adj circuit) and backside same (polymer or epoxy or  | IBM_TDB                |                  |
|          |         | epoxies or silicone or urethane or siloxane or parylene) same   |                        |                  |
|          |         | (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or  | ,                      |                  |
|          |         | planaris\$4))   | LICOAT                 | 0004/00/40 00:00 |
| -        | 23      | 1 ( · p · · · · · · · · · · · · · · · · ·   | USPAT;                 | 2004/09/18 20:33 |
|          |         | near8 coat\$4 near8 ((cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) or backgrind\$)                    | US-PGPUB;              |                  |
| •        | į       | or planarizat or planarisat) or backgrings)   | EPO; JPO;              |                  |
|          |         |   | DERWENT;<br>IBM_TDB    |                  |
| 1_       | 15      | ( (chip or die or dice or ic or integrated adj circuit) and backside  | USPAT;                 | 2004/09/18 20:20 |
|          | "       | near8 coat\$4 near8 ((cmp or chemical adj mechanical or polish\$4   | US-PGPUB;              | 2004/03/10 20:20 |
|          |         | or planariz\$4 or planaris\$4) or backgrind\$)) not (backside near4   | EPO; JPO;              |                  |
|          |         | (chip or die or dice or ic or integrated adj circuit) and backside  | DERWENT;               |                  |
|          |         | near8 coat\$4 near8 ((cmp or chemical adj mechanical or polish\$4   | IBM_TDB                |                  |
|          |         | or planariz\$4 or planaris\$4) or backgrind\$))   | <u>-</u>               |                  |
| -        | 6       | (chip or die or dice or ic or integrated adj circuit) and backside  | USPAT;                 | 2004/09/18 20:30 |
|          |         | near8 passivat\$4 near8 ((cmp or chemical adj mechanical or   | US-PGPUB;              |                  |
|          |         | polish\$4 or planariz\$4 or planaris\$4) or backgrind\$)  | EPO; JPO;              |                  |
|          |         |   | DERWENT;               |                  |
|          |         |   | IBM_TDB                |                  |
| -        | 198     | (chip or die or dice or ic or integrated adj circuit) and backside  | USPAT;                 | 2004/09/18 20:34 |
|          |         | same coat\$4 same ((cmp or chemical adj mechanical or polish\$4   | US-PGPUB;              |                  |
| ľ        |         | or planariz\$4 or planaris\$4) or backgrind\$)  | EPO; JPO;              |                  |
|          |         |   | DERWENT;               |                  |
|          | 175     | ( (ahip or die or dies or is or integrated adi sireit) and backside   | IBM_TDB                | 0004/00/40 00:00 |
| -        | 175     | ((chip or die or dice or ic or integrated adj circuit) and backside same coat\$4 same ((cmp or chemical adj mechanical or polish\$4 | USPAT;                 | 2004/09/18 22:08 |
|          |         | or planariz\$4 or planaris\$4) or backgrind\$)) not ( (chip or die or   | US-PGPUB;              |                  |
|          | i       | dice or ic or integrated adj circuit) and backside near8 coat\$4  | EPO; JPO;<br>DERWENT;  | 1                |
|          |         | near8 ((cmp or chemical adj mechanical or polish\$4 or planariz\$4  | IBM_TDB                |                  |
|          |         | or planaris\$4) or backgrind\$))  | 15155                  |                  |
| -        | 6       |   | USPAT;                 | 2004/09/18 20:34 |
|          |         | same coat\$4 same ((cmp or chemical adj mechanical or polish\$4   | US-PGPUB;              |                  |
|          |         | or planariz\$4 or planaris\$4) or backgrind\$)).ab.   | EPO; JPO;              |                  |
| }        |         |   | DERWENT;               |                  |
|          |         |   | IBM_TDB                |                  |
| -        | 2185088 | polymer or epoxy or epoxies or silicone or urethane or siloxane or  | USPAT;                 | 2004/09/18 22:09 |
|          |         | parylene  | US-PGPUB;              |                  |
|          | ]       |   | EPO; JPO;              |                  |
|          |         |   | DERWENT;               |                  |
| _        | 1300622 | peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven  | IBM_TDB                | 2004/00/49 22:54 |
|          | 1300022 | Peaks of validys of fill of filliocks of foughter of Jagged of uneven   | USPAT;<br>US-PGPUB;    | 2004/09/18 22:54 |
|          |         |   | EPO; JPO;              |                  |
|          |         |   | DERWENT;               |                  |
|          |         |   | IBM_TDB                |                  |
| <b>-</b> | 1632127 | chip or die or dice or ic or integrated adj circuit   | USPAT;                 | 2004/09/18 22:20 |
|          |         | <b>3</b>  | US-PGPUB;              |                  |
|          |         |   | EPO; JPO;              |                  |
|          |         |   | DERWENT;               |                  |
|          |         |   | IBM_TDB                |                  |
| -        | 293421  | cmp or chemical adj mechanical or polish\$4 or planariz\$4 or   | USPAT;                 | 2004/09/18 22:12 |
|          |         | planaris\$4   | US-PGPUB;              |                  |
|          |         |   | EPO; JPO;              |                  |
|          |         |   | DERWENT;               |                  |
| _        | 4042332 | smooth\$6 or even\$4  | IBM_TDB                | 0004/00/40 00 40 |
| -        | 4042332 | SHOOTHOO OF EVERION   | USPAT;                 | 2004/09/18 22:12 |
|          |         |   | US-PGPUB;<br>EPO; JPO; |                  |
|          |         |   | DERWENT;               |                  |
|          |         |   | IBM TDB                |                  |
|          |         |   |                        | L                |

| Citip or die or dice or ice or integrated adj circuit ) and (peaks or valleys or fill or hillotics, or rough\$4 or lagged or uneven) nead (polymer or epoxy or spoxies or silicone or urethane or siloxane or partnariz\$4 or planaris\$4 ) nead (smooth\$6 or veren\$4) (citip or die or dice or ice integrated adj circuit ) and (peaks or valleys or hill or hillotics) or integrated adj circuit ) and (peaks or valleys or hill or hillotics) or integrated adj circuit ) and (peaks or valleys or hill or hillotics) or rough\$4 or jagged or uneven) nead (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) neaf (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) same (smooth\$6 or even\$4) (ship or die or dice or ice or integrated adj circuit ) and sacrificial\$4 neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) neard (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 or planaris\$4 or planaris\$5 or planaris\$4 or planaris\$5 or planaris\$4 or planaris\$4 or planaris\$5 or planaris\$4 or planaris\$4 or planaris\$4 or planaris\$5 or planaris\$5 or even\$4) (chip or die or dice or ice or integrated adj circuit ) and sacrificial\$4 neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) neard (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 or planaris\$5 or planaris\$5 or planaris\$5 or planaris\$5 or planaris\$4 or planaris\$5 or planaris\$4 or planaris\$5 or planaris\$5 or planaris\$5 or planaris\$5 or planaris\$4 or planaris\$5  |    |         |   | <del>-</del> |                  |
|--|----|---------|---|--------------|------------------|
| (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene ) near6 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) near6 (smooth\$6 or even\$4)  161 (chip or die or die or to ir nitegrated adj circuit ) and (peaks or valleys or hill or hillocks or rough\$4 or lagged or uneven) same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or planaris\$4) same (smooth\$6 or even\$4)  1632127 (chip or die or dice or ic or integrated adj circuit ) and (peaks or valleys or planarix\$4 or planaris\$4) and planarix\$4 or planarix                             | -  | 1       | (chip or die or dice or ic or integrated adj circuit ) and (peaks or      | USPAT;       | 2004/09/18 22:14 |
| or panyfene ) near6 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near6 (monoth\$6 or even\$4) (chip or die or diee or ic or integrated adj circuit ) and (peaks or valleys or hill or hillocks or rough\$4 or lagged or uneven) same (polymer or epoxy or epoxies or silicone or urethane or palyene) same (polymer or epoxy or epoxies or silicone or urethane or planariz\$4 or planaris\$4) same (smooth\$6 or even\$4) (chip or die or diee or ic or integrated adj circuit ) and (peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven) near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or panyfene) near6 (cmp or chemical adj mechanical or polish\$4 or planaris\$4) planaris\$4 or planaris\$4) planaris\$4 or planaris\$4 planaris\$4 or planaris\$4 planaris\$                 |    |         |   |              |                  |
| or planariz\$4 or planaris\$4) near6 (smooth\$6 or even\$4)  16 (chip or die or dice or ic or integrated adj circuit) and (speaks or valleys or hill or hillocks or rough\$4 or jagged or uneven) same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) same (smooth\$6 or even\$4)  14 (chip or die or dice or ic or integrated adj circuit) and (peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven) near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) para6 (cmp or chemical adj mechanical or polish\$4 or planaris\$4)  1632127 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) hear8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4) planaris\$4 or planaris\$4   | İ  |         |   |              |                  |
| Chip or die or dice or ic or integrated adj circuit ) and (peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven) same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parlyene) same (polymer or epoxy or epoxies or silicone or urethane) or parlyene) and (polymer or epoxy or epoxies or silicone or urethane or siloxane or parlyene) near6 (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or pl                           | 1  |         |   |              |                  |
| valleys or hill or hillocks or rough\$4 or jagged or uneven) same (polymer or epoxy or epoxies or sillocone or urethane or silloxane or parylene) same (cmp or chemical adj mechanical or polish\$4 or planaris\$4 ) palma (mans\$4) and adj mechanical or polish\$4 or planaris\$4         | 1  |         |   |              |                  |
| (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) same (smooth\$6 or even\$4)   USPAT; US-PGPUB; EPO; JPO; DefaveNT; IBM, TOB USPAT; US-PGPUB; EPO  | -  | 161     |   |              | 2004/09/18 22:13 |
| 14   14   15   16   16   17   18   18   18   18   18   18   19   18   19   18   19   18   19   18   19   18   19   18   19   19  |    |         |   |              |                  |
| or planariz\$4 or planaris\$4) same (smooth\$6 or even\$4)  14 (thip or die or dice or ic or integrated adj circuit ) and (peaks or valleys or hill or hillocks or rough\$4 or jagaged or uneven) near4 (polymer or epoxy or epoxies or silicone or urethane or or parylene) near6 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) near4 (smooth\$6 or even\$4)  1632127 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near4 (polymer or epoxy or epoxies or silicone or urethane or polish\$4 or planariz\$4 or planaris\$4) near4 (smooth\$6 or even\$4)  10 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene ) near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) near4 (smooth\$6 or letthane or siloxane or parylene ) near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) same backside  13 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene ) near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4) or planaris\$4) or planaris\$4) or planaris\$4 or planaris\$4) or planaris\$4 or planaris\$4 or planaris\$4) or planaris\$4 or planaris\$4 or planaris\$4) near4 (smooth\$6 or even\$4)  18 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4) near4 (smooth\$6 or even\$4)  18 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4) near4 (smooth\$6 or even\$4)  18 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4) near4 (smooth\$6 or even\$4)  18 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish  |    |         |   |              |                  |
| Chip or dice or ice or integrated adj circuit ) and (peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven) near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near6 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planari                |    |         |   |              |                  |
| valleys or hill or hillocks or rough\$4 or jagged or uneven) neard (polymer or epoxy or epoxies or stilicone or urethane or siloxane or parylene) near6 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or          |    | 44      |   |              | 2004/00/40 22:40 |
| (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) nears (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4      | -  | 14      |   | -            | 2004/09/10 22.19 |
| or parylene ) nearis (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or plan |    |         |   |              |                  |
| or planariz\$4 or planaris\$4 ) chip or die or dice or ic or integrated adj circuit  - 0 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4) - 0 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or planaris\$4 ) near4 (smooth\$6 or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or planaris\$4 ) and sacrificial\$4 near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4) - 18 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4) - 18 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4) - 18 (chip or die or dice or ic or integrated adj circuit) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planarix\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4) - 2 2004/09/18 22:52 - 2 2004/08/554.pn 1632127 (chip or die or dice or ic or integrated adj circuit) - 1632127 (chip or die or dice or ic or integrated adj circuit) - 1632127 (chip or die or dice or ic or integrated adj circuit) - 1632127 (chip or die or dice or ic or integrated adj circuit) - 1632127 (chip or die or dice or ic or integrated adj circuit) - 17   |    |         |   |              |                  |
| 1632127  | 1  |         |   |              |                  |
| Chip or die or dice or ic or integrated adj circuit ) and sacrificials   SPGPUB;   S   | _  | 1632127 |   |              | 2004/09/18 22:20 |
| - 0 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 0 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) same backside  - 31 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) same backside  - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 (chip or die or dice or ic or integrated adj circuit ) us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB; EPO; JPO; DERWENT; IBM TDB US.PAT; Us.PGPUB   |    | 1002127 | crip of the of the of integrated adjunctif                                |              | 2004/03/10 22.20 |
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| polish\$4 or planariz\$4 or planaris\$4 )  (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planariz\$4 ) near4 (smooth\$6 or even\$4)  18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 planariz\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  19 (chip or die or dice or ic or integrated adj circuit )  10 (chip or die or dice or ic or integrated adj circuit )  10 (chip or die or dice or ic or integrated adj circuit )  11 (chip or die or dice or ic or integrated adj circuit )  12 (chip or die or dice or ic or integrated adj circuit )  13 ((chip or die or dice or ic or integrated adj circuit )  14 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  15 ((chip or die or dice or ic or integrated adj circuit )  16 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  18 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  |    |         |   |              |                  |
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| planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  [EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;  | -  | 10      |   |              | 2004/09/10 22.40 |
| - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 2 20040065554.pn.  2 20040065554.pn.  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  |    |         |   |              |                  |
| - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 2 20040065554.pn.  2 20040065554.pn.  1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  18 ((chip or die or dice or ic or integrated adj circuit )  18 ((chip or die or dice or ic or integrated adj circuit )  18 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  18 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  2004/09/18 22:52  2004/09/18 22:52  2004/09/18 22:52  2004/09/18 22:52  2004/09/18 22:52  2004/09/18 22:52  2004/09/18 22:53   |    |         | plananzy+ or plananoy+ / noar+ (omoosiyo or oveny+)                       |              |                  |
| - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 2 20040065554.pn.  2 20040065554.pn.  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 18 (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  |    |         |   |              |                  |
| near8 (cmp or chemical adj mechanical or pollsh\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  US-PGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; US  | -  | 18      | (chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 |              | 2004/09/18 22:52 |
| planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  2 20040065554.pn.  2 20040065554.pn.  2 20040065554.pn.  2 20040065554.pn.  3 2004/09/18 22:47  4 2004/09/18 22:47  5 2004/09/18 22:52  5 2004/09/18 22:52  5 2004/09/18 22:52  6 2004/09/18 22:52  1 6 3 2 1 2 7  1 6 3 2 1 2 7  1 6 3 2 1 2 7  1 6 3 2 1 2 7  1 6 3 2 1 2 7  1 6 3 2 1 2 7  1 6 3 2 1 2 7  1 7 2 7  1 8 ((chip or die or dice or ic or integrated adj circuit)  1 8 ((chip or die or dice or ic or integrated adj circuit)) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  2 9 2 0 0 4 / 0 9 / 18 22:52  2 0 0 4 / 0 9 / 18 22:52  2 0 0 4 / 0 9 / 18 22:52  3 2 0 0 4 / 0 9 / 18 22:52  4 2 0 0 4 / 0 9 / 18 22:52  4 2 0 0 4 / 0 9 / 18 22:52  4 2 0 0 4 / 0 9 / 18 22:52  4 2 0 0 4 / 0 9 / 18 22:52  5 2 0 0 4 / 0 9 / 18 22:53  5 2 0 0 4 / 0 9 / 18 22:53  5 3 2 0 0 4 / 0 9 / 18 22:53  5 3 2 0 0 4 / 0 9 / 18 22:53  5 3 2 0 0 4 / 0 9 / 18 22:53  5 3 2 0 0 4 / 0 9 / 18 22:53  5 3 2 0 0 4 / 0 9 / 18 22:53  5 3 2 0 0 4 / 0 9 / 18 22:53  5 4 2 0 0 4 / 0 9 / 18 22:53  6 5 2 0 0 4 / 0 9 / 18 22:53  7 5 2 0 0 4 / 0 9 / 18 22:53  7 6 7 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0   |    |         |   |              |                  |
| - 2 20040065554.pn.  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWE   |    |         |   |              |                  |
| - 2 20040065554.pn. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; ISPO; JPO; DERWENT; JPO; JPO; DERWENT; ISPO; JPO; DERWENT; ISPO; JPO; DERWENT; ISPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J   |    | ĺ       |   |              |                  |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  - 2004/09/18 22:47 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PG   | }  |         |   | •            |                  |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)    EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISPO; JPO;   | -  | 2       | 20040065554.pn.   | USPAT;       | 2004/09/18 22:47 |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and Sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISPO; JPO; DERWENT; IS   |    |         |   |              |                  |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)    IBM_TDB   |    |         |   |              |                  |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;   |    |         |   |              |                  |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;  |    | 400010- |   |              | 0004/00/40 55 55 |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;   | 1- | 1632127 | (cnip or die or dice or ic or integrated adjicircuit )                    | •            | 2004/09/18 22:52 |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  DERWENT; IBM_TDB USPAT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; IBM   |    |         |   |              |                  |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)    IBM_TDB   US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   US-PGPUB; IS-PGPUB; IS-PG   |    |         |   |              |                  |
| - 1632127 (chip or die or dice or ic or integrated adj circuit )  - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and   |    |         |   |              |                  |
| - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planaris\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  US-PGPUB; EPO; JPD; US-PGPUB; EPO; JPO; DERWENT;  | 1_ | 1632127 | (chip or die or dice or ic or integrated adj circuit )                    |              | 2004/00/49 22:52 |
| - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT;   | -  | 1002127 | (only of the of those of to of integrated any distuit)                    |              | 2004/03/10 22:32 |
| - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;  |    |         |   |              |                  |
| - 18 ((chip or die or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)    BM_TDB  |    |         |   |              |                  |
| - 18 ((chip or dice or ic or integrated adj circuit ) ) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  USPAT; US-PGPUB; EPO; JPO; DERWENT;  |    |         |   |              |                  |
| sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)  EPO; JPO; DERWENT;   | -  | 18      | ((chip or die or dice or ic or integrated adj circuit ) ) and             |              | 2004/09/18 22:53 |
| or planariz\$4 or planaris\$4 ) near4 (smooth\$6 or even\$4)   |    |         | sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4         | -            |                  |
| DERWENT;   |    |         |   | EPO; JPO;    |                  |
| IBM_TDB  | 1  |         |   | DERWENT;     |                  |
|  | L  |         |   | IBM_TDB      |                  |

| -          | 1133    | ((chip or die or dice or ic or integrated adj circuit)) and sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4 | USPAT;<br>US-PGPUB; | 2004/09/18 22:54 |
|------------|---------|---|---------------------|------------------|
|            |         | or planariz\$4 or planaris\$4)  | EPO; JPO;           |                  |
|            |         | of planane or planane y   | DERWENT;            |                  |
|            |         |   | IBM_TDB             |                  |
| l <u>-</u> | 1300622 | peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven  | USPAT;              | 2004/09/20 11:42 |
|            | 1300022 | peaks of valleys of filli of filliooks of foughtp4 of jagged of different   | US-PGPUB;           | 2004/03/20 11.42 |
|            |         |   | EPO; JPO;           |                  |
|            |         |   | DERWENT;            |                  |
|            |         |   | IBM_TDB             |                  |
| l _        | 12      | ((chip or die or dice or ic or integrated adj circuit ) ) and (peaks or   | USPAT;              | 2004/09/18 22:54 |
| •          | '2      | valleys or hill or hillocks or rough\$4 or jagged or uneven ) near8   | US-PGPUB;           | 2004/03/10 22.54 |
|            |         | sacrificial\$4 near8 (cmp or chemical adj mechanical or polish\$4   | EPO; JPO;           |                  |
|            |         | or planariz\$4 or planaris\$4)  | DERWENT;            |                  |
|            |         | or planarized or planarised j   | IBM_TDB             |                  |
| _          | 1300622 | peaks or valleys or hill or hillocks or rough\$4 or jagged or uneven  | USPAT;              | 2004/09/20 11:42 |
| -          | 1300022 | peaks of valleys of fill of filllocks of foughter of jagged of different  | US-PGPUB;           | 2004/05/20 11.42 |
|            |         |   | EPO; JPO;           |                  |
|            |         |   |                     |                  |
|            |         |   | DERWENT;            |                  |
|            | 1632127 | ship or die or dies or is or integrated adj sirguit   | IBM_TDB             | 2004/00/20 11:42 |
| -          | 1032121 | chip or die or dice or ic or integrated adj circuit   | USPAT;              | 2004/09/20 11:43 |
|            |         |   | US-PGPUB;           |                  |
|            |         |   | EPO; JPO;           |                  |
|            |         |   | DERWENT;            |                  |
|            | 2105000 | polymor or analysis are allianne as weathern as allevens as   | IBM_TDB             | 0004/00/20 44:42 |
| -          | 2185088 | polymer or epoxy or epoxies or silicone or urethane or siloxane or  | USPAT;              | 2004/09/20 11:43 |
|            |         | parylene  | US-PGPUB;           |                  |
|            |         |   | EPO; JPO;           |                  |
|            |         |   | DERWENT;            |                  |
|            | 202424  |   | IBM_TDB             | 0004/00/00 44:40 |
| -          | 293421  | cmp or chemical adj mechanical or polish\$4 or planariz\$4 or   | USPAT;              | 2004/09/20 11:43 |
|            |         | planaris\$4   | US-PGPUB;           |                  |
| ľ          |         |   | EPO; JPO;           |                  |
|            |         |   | DERWENT;            |                  |
|            | 400     | (ahin on die on dies on is an intermetad adi airavità) and (anti-mana)  | IBM_TDB             | 0004/00/00 44.45 |
| -          | 120     |   | USPAT;              | 2004/09/20 11:45 |
|            |         | epoxy or epoxies or silicone or urethane or siloxane or parylene)   | US-PGPUB;           |                  |
|            |         | near8 (cmp or chemical adj mechanical or polish\$4 or planariz\$4   | EPO; JPO;           |                  |
|            |         | or planaris\$4 ) near8 expos\$4   | DERWENT;            |                  |
|            | ے ا     | (abin or die or dies or is ar integrated adi sirevit \ ====0 (natures   | IBM_TDB             | 2004/00/00 42:40 |
| •          | 6       | (chip or die or dice or ic or integrated adj circuit ) near8 (polymer   | USPAT;              | 2004/09/20 13:18 |
|            |         | or epoxy or epoxies or silicone or urethane or siloxane or  | US-PGPUB;           |                  |
|            | •       | parylene ) near8 (cmp or chemical adj mechanical or polish\$4 or  | EPO; JPO;           |                  |
|            |         | planariz\$4 or planaris\$4 ) near8 expos\$4   | DERWENT;            |                  |
|            | 247     | (abin as die as dies as is as interpreted adi sissuit ) as as 0 (astumber   | IBM_TDB             | 0004/00/00 40:44 |
| -          | 217     |   | USPAT;              | 2004/09/20 16:11 |
|            |         | or epoxy or epoxies or silicone or urethane or siloxane or  | US-PGPUB;           | 1                |
|            |         | parylene ) and (cmp or chemical adj mechanical or polish\$4 or  | EPO; JPO;           |                  |
|            |         | planariz\$4 or planaris\$4 ) near4 expos\$4   | DERWENT;            |                  |
|            | 40      | (ohip or die or dies or in or integrated adi alreadt) as and (ast area  | IBM_TDB             | 2004/00/00 40:47 |
| -          | 13      |   | USPAT;              | 2004/09/20 13:17 |
|            |         | or epoxy or epoxies or silicone or urethane or siloxane or  | US-PGPUB;           |                  |
|            |         | parylene ) near8 (cmp or chemical adj mechanical or polish\$4 or  | EPO; JPO;           |                  |
|            |         | planariz\$4 or planaris\$4 ) near16 expos\$4  | DERWENT;            |                  |
|            | _ ا     | Ashin on die en dies en la se intermete d'estre (CA) es es O. C.  | IBM_TDB             | 0004/00/00 10 10 |
| -          | 6       | ( the first and a series of the armony and a series ( polytime)   | USPAT;              | 2004/09/20 13:18 |
|            |         | or epoxy or epoxies or silicone or urethane or siloxane or  | US-PGPUB;           |                  |
|            |         | parylene ) near8 (cmp or chemical adj mechanical or polish\$4 or  | EPO; JPO;           |                  |
|            |         | planariz\$4 or planaris\$4 ) near8 expos\$4   | DERWENT;            |                  |
|            | -       | (/ohip or dio or dio or is an interested add alequate \ \ ====0 (-1)  | IBM_TDB             | 0004/00/00 10 10 |
| -          | 7       | ( ( comp or are or area or real armogration and or out ) means (porymor   | USPAT;              | 2004/09/20 13:18 |
|            |         | or epoxy or epoxies or silicone or urethane or siloxane or  | US-PGPUB;           |                  |
|            |         | parylene ) near8 (cmp or chemical adj mechanical or polish\$4 or  | EPO; JPO;           |                  |
|            |         | planariz\$4 or planaris\$4 ) near16 expos\$4) not ((chip or die or  | DERWENT;            |                  |
|            |         | dice or ic or integrated adj circuit ) near8 (polymer or epoxy or   | IBM_TDB             |                  |
|            |         | epoxies or silicone or urethane or siloxane or parylene ) near8   |                     |                  |
|            |         | (cmp or chemical adj mechanical or polish\$4 or planariz\$4 or  |                     |                  |
| L          | L.      | planaris\$4 ) near8 expos\$4 )  | L                   |                  |

| -   | 8       | backside near4 (chip or die or dice or ic or integrated adj circuit)     | USPAT;                | 2004/09/20 13:24 |
|-----|---------|--|-----------------------|------------------|
|     |         | and backside same (polymer or epoxy or epoxies or silicone or            | US-PGPUB;             |                  |
|     |         | urethane or siloxane or parylene) same (cmp or chemical adj              | EPO; JPO;             |                  |
|     |         | mechanical or polish\$4 or planariz\$4 or planaris\$4) same              | DERWENT;              | :                |
|     | 1000107 | expos\$4   | IBM_TDB               | 0004/00/00 44 47 |
| -   | 1632127 | chip or die or dice or ic or integrated adj circuit                      | USPAT;                | 2004/09/20 14:47 |
|     |         |  | US-PGPUB;             |                  |
| 1   |         |  | EPO; JPO;             |                  |
|     |         |  | DERWENT;              |                  |
|     |         |  | IBM_TDB               |                  |
| -   | 2185088 | polymer or epoxy or epoxies or silicone or urethane or siloxane or       | USPAT;                | 2004/09/20 17:38 |
|     | -       | parylene   | US-PGPUB;             |                  |
| i   |         |  | EPO; JPO;             |                  |
|     |         |  | DERWENT;              |                  |
|     | 1414770 | sis? or "sis sub ?" or suids   | IBM_TDB               | 0004/00/00 44.40 |
| -   | 1414770 | sio? or "sio.sub.2" or oxide   | USPAT;                | 2004/09/20 14:49 |
|     |         |  | US-PGPUB;             |                  |
|     | 1       |  | EPO; JPO;             |                  |
|     |         |  | DERWENT;              |                  |
|     | 60162   | booksida   | IBM_TDB               | 2004/00/20 44-54 |
| -   | 60162   | backside   | USPAT;<br>US-PGPUB:   | 2004/09/20 14:54 |
| ļ   |         |  |                       |                  |
| ļ   |         |  | EPO; JPO;<br>DERWENT; |                  |
|     |         |  | IBM TDB               |                  |
| l _ | 1567914 | sio? or "sio.sub.2" or oxide or oxidiz\$4                                | USPAT;                | 2004/09/20 14:50 |
| -   | 1307314 | Sio: Of Sio.Sub.2 of Oxide of Oxidiz#4                                   | US-PGPUB;             | 2004/09/20 14.50 |
|     |         |  | EPO; JPO;             |                  |
| ŀ   |         |  | DERWENT;              |                  |
|     |         |  | IBM_TDB               |                  |
| 1_  | 2       | (chip or die or dice or ic or integrated adj circuit ) and backside      | USPAT;                | 2004/09/20 14:51 |
|     | _       | near4 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near4 (polymer         | US-PGPUB:             | 2004/05/20 14.51 |
|     |         | or epoxy or epoxies or silicone or urethane or siloxane or               | EPO; JPO;             |                  |
|     |         | parylene)  | DERWENT;              |                  |
| 1   |         | paryions /   | IBM TDB               |                  |
| -   | 1983    | expos\$4 near4 backside  | USPAT:                | 2004/09/20 14:51 |
|     |         |  | US-PGPUB;             |                  |
|     |         |  | EPO; JPO;             |                  |
| ]   |         |  | DERWENT;              |                  |
|     |         |  | IBM_TDB               |                  |
| -   | 0       | ((chip or die or dice or ic or integrated adj circuit ) and backside     | USPAT;                | 2004/09/20 14:55 |
|     | İ       | near4 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near4 (polymer         | US-PGPUB;             |                  |
|     |         | or epoxy or epoxies or silicone or urethane or siloxane or               | EPO; JPO;             |                  |
|     |         | parylene )) and (expos\$4 near4 backside)                                | DERWENT;              |                  |
|     |         |  | IBM_TDB               | 1                |
| -   | 25      | (  | USPAT;                | 2004/09/20 17:38 |
|     |         | near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer         | US-PGPUB;             |                  |
| ļ   |         | or epoxy or epoxies or silicone or urethane or siloxane or               | EPO; JPO;             |                  |
|     |         | parylene)  | DERWENT;              |                  |
|     |         |  | IBM_TDB               |                  |
| -   | 1       |  | USPAT;                | 2004/09/20 14:52 |
|     |         | near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer         | US-PGPUB;             |                  |
|     | 1       | or epoxy or epoxies or silicone or urethane or siloxane or               | EPO; JPO;             |                  |
|     | 1       | parylene )) and (expos\$4 near4 backside)                                | DERWENT;              |                  |
|     | 464     | (ohip or dip or dipp or in or intorested add sizes (t.) and the state of | IBM_TDB               | 0004/00/00 44.54 |
| -   | 161     |  | USPAT;                | 2004/09/20 14:54 |
|     |         | same (sio? or "sio.sub.2" or oxide or oxidiz\$4) same (polymer or        | US-PGPUB;             |                  |
| Ì   |         | epoxy or epoxies or silicone or urethane or siloxane or parylene)        | EPO; JPO;             |                  |
|     | 1       |  | DERWENT;              |                  |
| =   | 170202  | hookoido or hottom odi sido as filo adi sido as filo atda                | IBM_TDB               | 0004/00/00 17 17 |
| -   | 179323  | backside or bottom adj side or flip adj side or flipside                 | USPAT;                | 2004/09/20 17:40 |
|     |         |  | US-PGPUB;             |                  |
|     |         |  | EPO; JPO;             |                  |
|     |         |  | DERWENT;              |                  |
| L   | L       |  | IBM_TDB               | L                |

| 2004/09/20 15:07  |              |        |   |          |                  |
|---|--------------|--------|---|----------|------------------|
| epoxy or epoxies or silicone or urethane or alioxane or parylene  )   EPO; JPO;   | -            | 20     |   |          | 2004/09/20 15:07 |
| and (expos\$4 near4 backside)   |              |        |   | •        |                  |
| 10  |              | ļ      |   |          |                  |
| 0   |              |        | and (exposure near backside)  |          |                  |
| - 0 ("2003/099507"   "2003/0219912").PN. 0 ("2003/099507") or ("2003/0219912").PN. 1525 releas\$4 near4 "27" and (chip or die or dice or ic or integrated addicrouit) 1526 releas\$4 near4 "27" and (chip or die or dice or ic or integrated addicrouit) 1527 releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit) 1526 releas\$4 near4 (backside or bottom adj side or flipside) and (chip or die or dice or ic or integrated adj circuit) 1527 poc. DERWENT: IBM. TDB 1528-PG. JPO: DERWENT: IBM. TDB 1528-PG. J                          | _            | 0      | ("2003/0096507"   "2003/0219912").PN.                                   |          | 2004/09/20 15:07 |
| - 2 ("2003099507") or (20030219912"),PN. 1525 releas\$4 near4 "27" and (chip or die or dice or ic or integrated adj circuit ) 1526 releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit ) 1526 releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit ) 1571771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside or ide or ic or integrated adj circuit ) 1571771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside or inderside) same (chip or die or dice or ic or integrated adj circuit ) 1571771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside or inderside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flipside or underside) nearg (sio? or sis.os.b.2" or oxide or oxidis24) nearg (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) or (chip or dice or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) nearg (sio? or sis.os.b.2" or oxide or oxidis24) nearg (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) or (chip or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) nearg (sio? or sis.os.b.2" or oxide or oxidis24) nearg (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) in ott ((chip or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flipside) neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) in ott ((chip or dice or ic or integrated adj circuit ) neard (backside or bottom adj side or flipside) neard (polymer or epoxy or epoxies) or silicone or urethane or siloxane or parylene) in ott ((chip or dice or ic or i                           | -            | _      |   |          | · ·              |
| 2 ("20030996507") or ("20030219912")).PN. 1525 releas\$4 near4 "27" and (chip or die or dice or ic or integrated adj circuit) 1526 releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit) 1526 releas\$4 near4 (backside or bottom adj side or flipside) and (chip or die or dice or ic or integrated adj circuit) 1527 releas\$4 near4 (backside or bottom adj side or flipside or flipside or backside or bottom adj side or flip or back) adj side or flipside or Underside flipside or underside flipside or underside flipside or underside flipside or underside flipside or integrated adj circuit) 1527 releas\$4 near4 (backside or bottom adj side or flip or back or under) adj side or flipside or underside flipside or underside) same (chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or flipside) flipside or underside) same (chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or flipside) flipside or underside) flipside) flipside or underside) flipside) flipsi                         | _            | 0      |   |          |                  |
| releas\$4 near4 "27" and (chip or die or dice or ic or integrated adj circuit )  269 releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit )  309631 backside or bottom adj side or (flip or back) adj side or flipside)  backside or bottom adj side or (flip or back) adj side or flipside backside or bottom adj side or (flip or back or under) adj side or flipside or underside adj circuit )  142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside adj circuit )  142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside adj circuit )  144 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) eard (sio" or "sio. sub." or oxide or oxidix34) neard (polymer or epoxy or epoxies or sillicone or urethane or silloxane or parylene) )  1597 (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) nearg (sio" or "sio. sub." or oxide or oxidix34) nearg (polymer or epoxy or epoxies or sillicone or urethane or silloxane or parylene) ) not ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) nearg (sio" or "sio. sub." or oxide or oxidix34) nearge (polymer or epoxy or epoxies or sillicone or urethane or silloxane or parylene) in ott ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flipside) neard (polymer or epoxy or epoxies or sillicone or urethane or silloxane or parylene) in ott ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flipside) neard (polymer or epoxy or epoxies or sillicone or urethane or silloxane or parylene) in ott ((chip or die or dice or ic or integrated adj circuit ) neard (backside or bottom adj side or flipside) ne                         | -            | 2      | (("20030096507") or ("20030219912")).PN.                                | USPAT;   | 2004/09/20 16:11 |
| circuit )  circuit )  releas\$4 near4 (backside or bottom adj side or flip adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  adj side or flipside)  backside or bottom adj side or (flip or back) adj side or flipside  backside or bottom adj side or (flip or back) adj side or flipside  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside or underside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 (backside or bottom adj side or flipside)  releas\$4 near4 ( | İ            |        |   | US-PGPUB |                  |
| releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit )  571771 backside or bottom adj side or (flip or back) adj side or flipside Dackside or bottom adj side or (flip or back or under) adj side or flipside or underside)  142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside)  144 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit)  145 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) neard (sio? or sio.sub.2 or oxide or oxidiz\$4) neard (polymer or epoxy or epoxies or sillcone or urethane or siloxane or parylene) plot (chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) neard (sio? or sio.sub.2 or oxide or oxidiz\$4) neard (polymer or epoxy or epoxies or sillcone or urethane or siloxane or parylene) plot (chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) neard (sio? or sio.sub.2 or oxide or oxidiz\$4) neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) plot (chip or die or dice or ic or integrated adj circuit) and backside or bottom adj side or flipside) neard (backside or bottom adj side or flip adj side or flipside) neard (backside or bottom adj side or flip adj side or flipside) neard (backside or bottom adj side or flip adj side or flipside) neard (epoxy or epoxies)  1 5 0 ((chip or die or dice or ic or integrated adj circuit) neard (backside or bottom adj side or flip adj side or flipside) neard (epoxy or epoxies)  1 6 0 ((chip or die or dice or ic or integrated adj circuit) neard (backside or bottom adj side or flip adj side or flipside) neard (epoxy or epoxies) and (epoxy or epoxies) and                        | -            | 1525   | releas\$4 near4 "27" and (chip or die or dice or ic or integrated adj   |          | 2004/09/20 16:12 |
| releas\$4 near4 (backside or bottom adj side or flip adj side or flipside)  - 309631  - 309631  - 571771  backside or bottom adj side or (flip or back) adj side or flipside  - 571771  backside or bottom adj side or (flip or back or under) adj side or flipside  - 142  releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside  releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside)  - 142  releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside)  - 23  c(chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ) ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxy or epoxies or silicone or urethane or siloxane or parylene) ) ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxy or epoxies or silicone or urethane or siloxane or parylene) ) ((chip or die or dice or ic or integrated adj circuit )) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxy or epoxies or silicone or urethane or siloxane or parylene) not ((chip or die or dice or ic or integrated adj circuit )) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)  - 399333  - 48  (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies) )  (chip or die or dice or ic or integrated a                      |              |        | circuit)  |          |                  |
| releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit )  309631 backside or bottom adj side or (flip or back) adj side or flipside  - 309631 backside or bottom adj side or (flip or back or under) adj side or flipside or underside  - 371771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside  - 142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or 'sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ) and backside near6 (sio? or 'sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxyles or silicone or urethane or siloxane or parylene) ) and backside near6 (sio? or or sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxyles or silicone or urethane or siloxane or parylene) ) and backside near6 (sio? or or sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxyles or silicone or urethane or siloxane or parylene) ) ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies) ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies) ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies) ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies) ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies) ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bott                       |              |        |   |          |                  |
| releas\$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit )  available or flipside or flipside or flipside or flipside or flipside or flipside or underside or underside or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flipside or underside) same (chip or die or dice or bottom adj side or flipside or underside) same (chip or die or dice or bottom adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flipside or underside) same (chip or back or under) adj side or flipside or underside) same (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) (chip or die or dice or ic or integrated adj circuit ) near4 (poxylene or poxylene) (poxylene)                        |              |        |   |          |                  |
| flipside) and (chip or die or dice or ic or integrated adj circuit )  309631 backside or bottom adj side or (flip or back) adj side or flipside  571771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside  142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or under) adj side or flipside or in or integrated adj circuit )  142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or in or integrated adj circuit )  142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or dice or ic or integrated adj circuit )  144 (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near6 (sof) or "sio.sub.2" or oxide or oxide2\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near6 (sof) or "sio.sub.2" or oxide or oxide2\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ) not ((chip or die or dice or ic or integrated adj circuit ) and backside near6 (sof) or "sio.sub.2" or oxide or oxide2\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ) not ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies or silicone or urethane or siloxane or parylene) (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  148 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies )  159 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or e                        |              | 260    | released again (haskeide as betters adi aide as fin adi aide as         |          | 0004/00/00 40:40 |
| - 309631 backside or bottom adj side or (flip or back) adj side or flipside - 571771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside - 142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flip adj side or flipside or underside) near8 (sio? or *iso.sub.2* or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit) and (backside or underside) near8 (sio? or *iso.sub.2* or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or *iso.sub.2* or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or *iso.sub.2* or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or *iso.sub.2* or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)  - 399333 (chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies) pand ((expox\$4) or emox\$4\) near8 (polymer or epoxy or epoxies)  - 0 ((chip or die or dice or ic or integrated adj circuit) near4 (epoxy or epoxies) pand ((expox\$4\) or emox\$4                    | <del>-</del> | 269    |   |          | 2004/09/20 16:13 |
| - 309631 backside or bottom adj side or (flip or back) adj side or flipside  - 571771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside  - 142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or underside) same (chip or die or dice or ic or integrated adj circuit) and (backside or underside) near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ((chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside underside) near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene) (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies)  - 399333 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies) (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (poxy or epoxies) (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside                        |              |        | impside) and (chip of die of dice of ic of integrated adj circuit )     |          |                  |
| - 309631 backside or bottom adj side or (flip or back) adj side or flipside  - 571771 backside or bottom adj side or (flip or back or under) adj side or flipside or underside  - 142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside)  - 142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)  - 7 ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flip or back or under) adj side or flipside or underside) neard (sio? or "sio.sub.2" or oxide or oxidiz\$4) neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) in ((chip or die or dice or ic or integrated adj circuit ) and (backside underside) neard (sio? or "sio.sub.2" or oxide or oxidiz\$4) neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) in ((chip or die or dice or ic or integrated adj circuit ) and backside neard (sio? or "sio.sub.2" or oxide or oxidiz\$4) neard (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) in ((chip or die or dice or ic or integrated adj circuit ) and backside or bottom adj side or flip adj side or flipside) near4 (poxy or epoxies)  - 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside ure parylene) in ((chip or die or flip adj side or flipside) near4 (epoxy or epoxies) ) and ((expos\$4 or remov\$4) near4 (backside ure parylene) in ((chip or die or dice or ic or integrated adj circuit ) near4 (backside ure parylene) in ((chip or die or dice or ic or integrated adj circuit ) near4 (backside ure parylene) in ((chip or die or dice or ic or integrated adj circuit ) near4 (backside ure parylene) in ((chip or die or dice or ic or integrated adj circuit ) near                       |              |        |   |          |                  |
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| BM TDB   USPAT; USPGPUB; PO; JPO; DERWENT; Polymer or epoxy or epoxies or or parylene ) not ((chip or die or dice near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or bottom adj side or flipside) near4 (packside or oxidioxane or parylene)   epoxy or epoxies or bottom adj side or flipside) near4 (epoxy or epoxies)   expoxy or epoxies or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies)   expoxy or epoxies or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies)   expoxy or epoxies or silicone or urethane or siloxane or parylene)   expoxy or epoxies or silicone or urethane or siloxane or parylene)   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies or silicone or urethane or siloxane or parylene   expoxy or epoxies   expoxy or epoxies   expoxy or epoxies   expoxy or epoxies   expoxy or epoxies   expoxy or epoxies   expoxy or epoxies   expoxy or epoxies                               |              |        |   |          |                  |
| flipside or underside  releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flip or back or under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near4 (sio? or 'sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene ) (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or 'sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene ) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or 'sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) ) not ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)  48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies) and ((expos\$4 or remox\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside                         |              |        |   |          |                  |
| - 142 releas\$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or or dipside or underside) near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit) and backside near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit) and backside near6 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near6 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies) and ((expos\$4 or remox\$4) near6 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside) near4 (backside) near4 (backside) nea                       | -            | 571771 |   | USPAT;   | 2004/09/20 16:13 |
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| under) adj side or flipside or underside) same (chip or die or dice or lice or lic or integrated adj circuit )  32 (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or sloxane or parylene )  7 ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or sloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or sloxane or parylene )) epoxy or epoxies or silicone or urethane or sloxane or parylene )) epoxy or epoxies or silicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies or slicone or urethane or sloxane or parylene )) epoxy or epoxies )  4 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side                         |              |        |   |          |                  |
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| - 32 (chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )  ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  4 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  5 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  6 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  7 (chip or die or dice or ic or integrated adj circu                           |              |        |   |          |                  |
| Section   Comparison   Compar                                |              |        | or ic or integrated adjicircuit )                                       |          |                  |
| Chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene ) ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane                             |              |        |   |          |                  |
| bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)  7 ((chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies or silicone or urethane or siloxane or siloxane or parylene or poxylene) epoxylene)) epoxylene or poxylene)) epoxylene or poxylene)) epoxylene or poxylene)) epoxylene or poxylene or poxylene)) epoxylene or poxylene                         | _            | 32     | (chip or die or dice or ic or integrated adj circuit ) and (backside or |          | 2004/09/20 16:49 |
| underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)  ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit ) near4 (poxy or epoxies)  48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  4 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  4 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  4 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  4 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  5 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  6 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies))  7 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies))  8 ((chip or die or dice or ic or integrated adj circuit ) near4 (epoxy or epoxies))  9 ((chip or die or dice or ic or integrated adj circuit ) near4 (epoxy or                           | -            | 02     |   |          | 2004/05/20 10.45 |
| (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)  ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene))  - 399333 (chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)  - 48 (chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  - 0 ((chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))   |              |        |   |          |                  |
| or parylene )  ((chip or die or dice or ic or integrated adj circuit ) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies or silicone or urethane or siloxane or parylene )  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) epoxies )) epoxies or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj                            | 1            | ľ      |   |          |                  |
| or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene))  - 399333 epoxy or epoxies   |              |        | or parylene )   |          |                  |
| underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) epoxy or epoxies  - 399333  (chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)  - 0 ((chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies))  - 4 (expos\$4 or remov\$4) near4 (backside or flipside) near4 (epoxy or epoxies))  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies))  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies))  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies))  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies)  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies)  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside)  (expos\$4 or remov\$4) near4 (backside or flipside)  (expos\$5 or remov\$4) near4 (backside or flipside)  (expos\$5 or remov\$4) near4 (backside or flipside)  (expos\$6 or remov\$6) near4 (epoxy or epoxies)  | -            | 7      |   | USPAT;   | 2004/09/20 16:49 |
| (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies  - 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flip adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies)  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies)  - 5  |              |        |   |          |                  |
| or parylene )) not ((chip or die or dice or ic or integrated adj circuit ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene ))  approx or epoxies  48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies ))  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (backside or bottom adj side or flipside) near4 (backside or flipside) near4 (epoxy or epoxies )  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flipside) near4 (backside or flips                             |              |        |   |          |                  |
| ) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz\$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies  48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies ))  4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  (expos\$4 or remov\$4) near4 (epoxy or epoxies )   |              |        |   |          |                  |
| near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene )) epoxy or epoxies  2004/09/20 18:59  USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; DERWENT; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; D                              |              |        |   | IBM_TDB  |                  |
| siloxane or parylene )) epoxy or epoxies  2004/09/20 18:59  USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   |              |        |   |          |                  |
| - 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bettom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 2004/09/20 17:42  2004/09/20 17:42  2004/09/20 17:42  2004/09/20 17:42  2004/09/20 17:42  2004/09/20 17:42  | 1            |        |   |          |                  |
| 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  0 ((chip or die or dice or ic or integrated adj circuit ) near4 (epoxy or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  1 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flip adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  2 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side                          | _            | 399333 |   | USPAT.   | 2004/09/20 18:50 |
| - 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flip adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip a                          |              |        |   |          | 200-700/20 10.03 |
| - 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or flipside) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipside) near4 (epoxy or epoxies ))  - 5 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flipadj side or fli                      |              | 1      |   |          |                  |
| - 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies )  5 (chip or die or dice or ic or integrated adj circuit ) near4 (backside ISPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;  |              | 1      |   |          |                  |
| - 48 (chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  - 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or f                            |              |        |   |          |                  |
| epoxies )  ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip                            | -            | 48     |   | USPAT;   | 2004/09/20 17:41 |
| - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj si                            |              |        | ,                                 |          |                  |
| - 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj si                            |              |        | epoxies)  |          |                  |
| 0 ((chip or die or dice or ic or integrated adj circuit ) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies )  2004/09/20 17:42  USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;   | i            |        |   |          |                  |
| (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies )  2004/09/20 17:42 US-PGPUB; US-PGPUB; EPO; JPO; DERWENT; DERWENT;   |              |        | (/ahin an dia an dia an in an interpreta di adi territa di adi          |          |                  |
| (epoxy or epoxies )) and ((expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flip adj side or flipside) near4 (epoxy or epoxies )  EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;  | -            | l o    |   |          | 2004/09/20 17:42 |
| or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies ))  4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  USPAT; US-PGPUB; EPO; JPO; DERWENT;   |              |        |   |          |                  |
| epoxies )) 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )    BM_TDB  |              |        |   |          |                  |
| 4 (expos\$4 or remov\$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies )  USPAT; US-PGPUB; EPO; JPO; DERWENT;  |              |        |   |          |                  |
| adj side or flipside) near4 (epoxy or epoxies )  US-PGPUB; EPO; JPO; DERWENT;   | ۱ -          | 4      |   |          | 2004/09/20 17:42 |
| EPO; JPO; DERWENT;  |              | [      |   |          | 2007/00/20 11.42 |
| DERWENT;  |              |        | ,/p/ / (-p/) =/ -p-////   |          |                  |
|   |              |        |   |          |                  |
|   |              |        |   |          |                  |

| US-PGFUB;   PO, IPO, DERWENT;   IBM, TDB   US-PGFUB;   PO, IPO, DE   |              | ·       |  |           | T                 |
|--|--------------|---------|--|-----------|-------------------|
| - 399333 epoxy or epoxies   EPO, JPO: DERWENT: IBM_TDB   USPAT: U.S.P.GPUB; EP   | -            | 1632127 | chip or die or dice or ic or integrated adj circuit  | USPAT;    | 2004/09/20 21:16  |
| - 399333 epoxy or epoxies  - 156266 thermoset\$6 or thermo adj set\$6  - 156266 thermoset\$6 or thermo adj set\$6  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer)  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (the themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (the themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (the themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (the themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (the themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (the themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (the themoset\$6 or the themoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$6) near4 (then themoset\$6 or thermo adj set\$6) and (remov\$   |              |         |  |           |                   |
| 156266   |              |         |  |           |                   |
| 399333   epoxy or epoxies   USFAT; US-RGPUB; EPC, JPC; DERWENT; IBM, TDB USPAT; US-RGPUB; EPC, JPC; DERWENT;  |              |         |  |           |                   |
| US-PGPUB: EPC, JPC; DERWENT; IBM_TDB USPAT; US-PGPUB: EPC, JPC;  |              |         |  | _         |                   |
| 156266   thermoset\$6 or thermo adj set\$6   SPC, JPC, DERWENT; IBM TDB USPAT; US-PGPUB; EPC, JPC, DERWENT; IB   | -            | 399333  | epoxy or epoxies   |           | 2004/09/20 19:00  |
| - 156266 thermoset\$6 or thermo adj set\$6  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies) near4 ((hip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 2026815 (epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies) near4 (pox) or epoxies) n   |              |         |  |           |                   |
| 156266   thermoset\$6 or thermo adj set\$6   SPAT: US-PGPUB; EPO; JPO; DERWENT; IBM, TDB USPAT: US-PGPUB; EPO; JPO; DERWENT; IBM, TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM, TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM, TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM, TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM, TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM, TDB USPAT; US-PGPUB; EPO;  |              |         |  |           |                   |
| 156266   |              |         |  |           |                   |
| - 2026815 substrate or wafer  - 4671698 remov\$4 or etch\$4 or expos\$4  - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate) or wafer) or surface)  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (poxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (spoxy or epoxies )  |              |         |  | IBM_TDB   |                   |
| - 2026815 substrate or wafer  - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6  | -            | 156266  | thermoset\$6 or thermo adj set\$6  |           | 2004/09/20 19:00  |
| - 2026815 substrate or wafer  - 4671698 remov\$4 or etch\$4 or expos\$4  - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)   |              | ,       |  |           |                   |
| 2026815   substrate or wafer     IBM, TDB   USPAT; US-PGPUB; EPC-J.PC-DERWENT; IBM, TDB   USPAT; US-PGPUB; EPC-J   |              |         |  |           |                   |
| 2026815   Substrate or wafer   USPĀT; USPGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPGPUB; EPO; JPO; DERWENT; ISM TDB USPĀT; USPGPUB; EPO; JPO; DERWENT;  |              |         |  | DERWENT;  |                   |
| - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$\$) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$\$) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 33 (chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - (chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 1632127 (chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near4 ((chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near4 ((chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near4 (undit or integrated adj circuit) and (epoxy or epoxies) near4 (undit or integrated adj circuit) and (epoxy or epoxies) near4 (undit or integrated adj circuit) and (epoxy or epoxies) near4 (undit or integrated adj circuit) and (epoxy or epoxies) near4 (undit or integrated adj circuit) and (epoxy or epoxies) near4 (undit or integrated adj circuit) and (epoxy or epoxies) near4 (undit or integrated adj circuit) and (epoxy or epoxies) near4 (epo  |              |         |  | IBM_TDB   |                   |
| - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4   | -            | 2026815 | substrate or wafer   | USPAT;    | 2004/09/20 19:08  |
| - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 393 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (ichip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 2026815 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or wafer0 or surface)  - 55 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies )  |              |         |  | US-PGPUB: |                   |
| - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 393 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (ichip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 2026815 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or wafer0 or surface)  - 55 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies )  |              |         |  | EPO; JPO; |                   |
| - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) n   |              |         |  |           |                   |
| - 4671698 remov\$4 or etch\$4 or expos\$4  - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) n   | •            |         |  | IBM TDB   |                   |
| SPCPUB; EPC; JPC; DERWENT; BM_TDB   SPAT; USPAT;  | _            | 4671698 | remov\$4 or etch\$4 or expos\$4  |           | 2004/09/20 19:18  |
| 3823   Chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)   USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; JPC; DERWENT; IBM_TDB USPAT; USPGPUB; EPC; JPC; JPC; JPC; JPC; JPC; JPC; JPC; J   |              |         | <b>'</b> '   |           |                   |
| - 3823 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 93 (chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4 or etch\$4 or expos\$5) near6 (memov\$4   |              |         |  |           |                   |
| Chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)   Ghip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)   Ghip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)   Chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)   Chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)   Chip or die or dice or ic or integrated adj circuit   Or (substrate or wafer) or surface)   Chip or die or dice or ic or integrated adj circuit   Or (substrate or wafer)   Or SerWent; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USP  |              |         |  |           |                   |
| Chip or die or dice or ic or integrated adj circuit ) and (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERW  |              |         |  |           |                   |
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| 1632127   1632   |              |         |  |           |                   |
| USPAT;   USPGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;   USPAT;   USPAT;   USPGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;   USP   |              |         | I mogration and or out / or (outportation water) or outladay   |           |                   |
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| or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 1632127 chip or die or dice or ic or integrated adj circuit  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 55 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (expos\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 expos\$4 near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 4003371 remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 expos\$4 near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 4120690 remov\$4 or etch\$4 or expos\$4) near4 or etch\$4 or expos\$4 or planariz\$4  - 4120690 remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4  - 4120690 remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4  - 4120690 remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4  - 4120690 remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4  - 4120690 remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4  |              |         | enovies I near8 (thermoset\$6 or thermo adi set\$6) and (remov\$4  |           | 2004/05/20 15.05  |
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| - 2026815 substrate or wafer  2026815 substrate or wafer  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)  - 55 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (remov\$4 or etch\$4] (remov\$4 or etch\$ | •            |         |  | 1         |                   |
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| - 2026815 substrate or wafer  - 2026815 substrate or wafer  - 169 (epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or expos\$4) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (epoxy or epoxies ) near4 (expoxy or epoxies ) near  |              |         |  |           |                   |
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| or (substrate or wafer) or surface)  - 4003371 remov\$4 or etch\$4  remov\$4 or etch\$4  - 4120690 remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;   | !            |         |  |           |                   |
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| - 4120690 remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4   | -            | 4003371 | remov\$4 or etch\$4  |           | 2004/09/20 19:18  |
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| -        | 14    | (epoxy or epoxies) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies) near4 expos\$4 near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;            | 2004/09/20 19:36 |
|----------|-------|---|---|------------------|
| -        | 64    | (remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies ) near4 expos\$4 near4 ((substrate or wafer) or surface)   | IBM_TDB<br>USPAT;<br>US-PGPUB;<br>EPO; JPO;             | 2004/09/20 19:40 |
|          | 12    | ((remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4   | DERWENT;<br>IBM_TDB<br>USPAT;                           | 2004/09/20 19:38 |
| -        |       | (epoxy or epoxies ) near4 expos\$4 near4 ((substrate or wafer) or surface)) and (thermoset\$6 or thermo adj set\$6)   | US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB           | 2004/03/20 19.36 |
| -        | 1     | (((remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies ) near4 expos\$4 near4 ((substrate or wafer) or surface)) and (thermoset\$6 or thermo adj set\$6)) not ((epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies ) near4 expos\$4 near4 ((chip or die or dice or ic or   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/20 19:38 |
| -        | 53    | integrated adj circuit ) or (substrate or wafer) or surface)) ((remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies ) near4 expos\$4 near4 ((substrate or wafer) or surface)) not ((epoxy or epoxies ) near8 (thermoset\$6 or thermo adj set\$6) and (remov\$4 or etch\$4 or cmp or polish\$4 or planariz\$4) near4 (epoxy or epoxies ) near4 expos\$4 near4 ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer) or surface)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/20 20:24 |
| -        | 20672 | (thermoset\$6 or thermo adj set\$6) near4 (epoxy or epoxies )   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/20 20:24 |
| -        | 215   | (epoxy or epoxies ) near4 (screen or stencil or spin) near coat\$4  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/20 20:25 |
| -        | 0     | partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies ) near4 (before or subsequent\$4) near4 apply\$4   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/20 20:28 |
| -        | 865   | partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies )  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/09/20 20:29 |
| -        | 3     | ((thermoset\$6 or thermo adj set\$6) near4 (epoxy or epoxies )) and ((epoxy or epoxies ) near4 (screen or stencil or spin) near coat\$4) and (partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies ) ) and ((chip or die or dice or ic or integrated  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;            | 2004/09/20 20:37 |
| -        | 42    | adj circuit ) or (substrate or wafer)) partial\$4 near2 (cur\$4 or set\$6 or harden\$4) near4 (epoxy or epoxies ) near4 (before or subsequent\$4)   | IBM_TDB<br>USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT; | 2004/09/20 20:32 |
| -        | 2     | tacky near4 (epoxy or epoxies ) near4 (before or subsequent\$4) near4 (coat\$4 or apply\$4)   | IBM_TDB<br>USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT; | 2004/09/20 20:39 |
| <u> </u> | L     |   | IBM_TDB   | L                |

| - | 144    | (epoxy or epoxies ) near4 (cur\$4 or harden\$4 or set\$6) near4 (before or subsequent\$4) near4 (coat\$4 or apply\$4)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;             | 2004/09/20 20:34   |
|---|--------|--|--|--------------------|
|   |        |  | DERWENT;<br>IBM_TDB                          |                    |
| - | 0      | ((epoxy or epoxies ) near4 (cur\$4 or harden\$4 or set\$6) near4 (before or subsequent\$4) near4 (coat\$4 or apply\$4)) and ((epoxy or epoxies ) near4 (screen or stencil or spin) near coat\$4) and | USPAT;<br>US-PGPUB;                          | 2004/09/20 20:39   |
|   |        | ((chip or die or dice or ic or integrated adj circuit ) or (substrate or wafer))   | EPO; JPO;<br>DERWENT;<br>IBM_TDB             |                    |
| - | 14     | (epoxy or epoxies ) near4 (hardener) near4 (before or subsequent\$4) near4 (coat\$4 or apply\$4)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;             | 2004/09/20 20:40   |
|   |        |  | DERWENT;<br>IBM_TDB                          |                    |
| - | 0      | subsequent\$4) near4 (coat\$4 or apply\$4)) and ((epoxy or epoxies ) near4 (screen or stencil or spin) near coat\$4) and ((chip or die   | USPAT;<br>US-PGPUB;<br>EPO; JPO;             | 2004/09/20 20:40   |
|   | 40000  | or dice or ic or integrated adj circuit ) or (substrate or wafer))   | DERWENT;<br>IBM_TDB                          | 000 4/00 /00 00 40 |
| - | 10282  | (epoxy or epoxies ) near4 (hardener)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;             | 2004/09/20 20:40   |
|   | _      | (  | DERWENT;<br>IBM_TDB                          | 0004/00/00 00:50   |
| - | 5      | ((epoxy or epoxies) near4 (hardener)) and ((epoxy or epoxies) near4 (screen or stencil or spin) near coat\$4) and ((epoxy or epoxies) or thermal\$4 or heat\$4) near4 (epoxy or epoxies)             | USPAT;<br>US-PGPUB;<br>EPO; JPO;             | 2004/09/20 20:59   |
|   |        |  | DERWENT;<br>IBM_TDB                          |                    |
| - | 223    | tape same releas\$4 near2 (film or layer) same backing and (chip or die or dice or ic or integrated adj circuit )  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT; | 2004/09/20 21:01   |
|   | 21     | tape near8 releas\$4 near2 (film or layer) near8 backing same  | IBM_TDB<br>USPAT;                            | 2004/09/20 21:09   |
|   |        | (chip or die or dice or ic or integrated adj circuit )   | US-PGPUB;<br>EPO; JPO;<br>DERWENT;           | 200 1/00/20 21:00  |
| - | 256    | tape near8 releas\$4 near2 (film or layer) near8 backing   | IBM_TDB<br>USPAT;                            | 2004/09/20 21:09   |
|   |        |  | US-PGPUB;<br>EPO; JPO;<br>DERWENT;           |                    |
| _ | 152599 | (chip or die or dice or ic or integrated adj circuit ) near4 (substrate  | IBM_TDB<br>USPAT;                            | 2004/09/20 21:12   |
|   |        | or wafer)  | US-PGPUB;<br>EPO; JPO;                       |                    |
| _ | 3      | (tape near8 releas\$4 near2 (film or layer) near8 backing) and   | DERWENT;<br>IBM_TDB<br>USPAT;                | 2004/09/20 21:14   |
|   |        | ((chip or die or dice or ic or integrated adj circuit ) near4 (substrate or wafer))  | US-PGPUB;<br>EPO; JPO;<br>DERWENT;           | 200 1/00/20 21:11  |
| _ | 168580 | ((chip or die or dice or ic or integrated adj circuit ) or packag\$4)  | IBM_TDB<br>USPAT;                            | 2004/09/20 21:14   |
|   |        | near4 (substrate or wafer)   | US-PGPUB;<br>EPO; JPO;<br>DERWENT;           |                    |
| - | 11     | (tape near8 releas\$4 near2 (film or layer) near8 backing) and   | IBM_TDB<br>USPAT;                            | 2004/09/20 21:15   |
|   |        | (((chip or die or dice or ic or integrated adj circuit ) or packag\$4) near4 (substrate or wafer))   | US-PGPUB;<br>EPO; JPO;<br>DERWENT;           |                    |
| L |        |  | IBM_TDB                                      |                    |

| - | 101 | (chip or die or dice or ic or integrated adj circuit ) near4 (backing  | USPAT;    | 2004/09/20 21:17 |
|---|-----|--|-----------|------------------|
|   |     | near4 tap\$4)  | US-PGPUB; |                  |
|   |     |  | EPO; JPO; |                  |
|   |     |  | DERWENT;  |                  |
|   |     |  | IBM TDB   |                  |
| - | 4   | (tape same releas\$4 near2 (film or layer) same backing and (chip      | USPAT:    | 2004/09/20 21:17 |
|   |     | or die or dice or ic or integrated adj circuit )) and ((chip or die or | US-PGPUB: |                  |
|   |     | dice or ic or integrated adj circuit ) near4 (backing near4 tap\$4))   | EPO: JPO: |                  |
|   |     |  | DERWENT:  |                  |
|   |     |  | IBM TDB   |                  |